

## everyday genius

# [8788\_Q] Thermal bring up SOP

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## **Document Revision History**

Revision	Date	Description	
0.1	2019-03-13	Initial Draft	
			20



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#### 1. Introduction

This document is about MT8788 thermal software configuration.

### 1.1 Purpose

This document is for customer to configure and use thermal in MT8788 Project.

#### 1.2 Definitions, Acronyms and Abbreviations

- bts: board thermal sensor
  - o It is thermal sensor mount on PCB board.

#### 1.3 References

No

#### 1.4 Overview

Sections overview. Such as:

Section 1 is the introduction and includes a description of the project.

Section 2 provides a system overview.

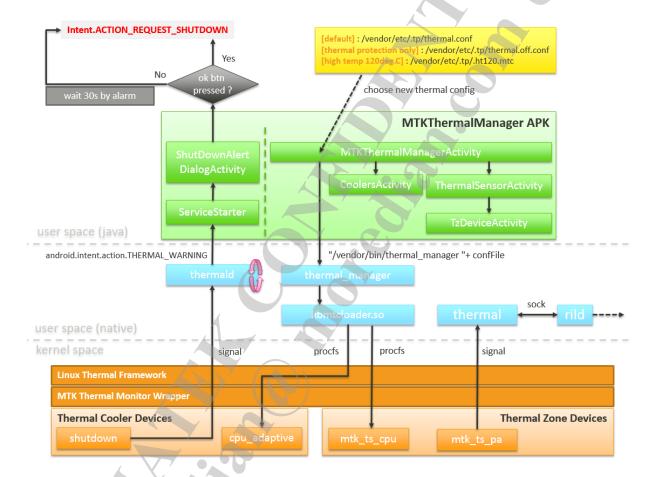
Section 3 describes what case would trigger reboot/shutdown.



## 2. Specific Contents

Thermal zone bind cooler by Linux thermal framework. Once temperature over trip point, corresponding cooler mechanism will be activated.

#### 2.1 Thermal architecture overflow





### 3 Notification

Thermal projecting function might trigger reboot/shutdown

## 3.1 What case would trigger reboot/shutdown

- NTC register table does not match with source code.
- AUXADC channel is not right one with source code.

#### 3.2 How to avoid

Return 0 degree of board sensor as workaround